圧電音響部品

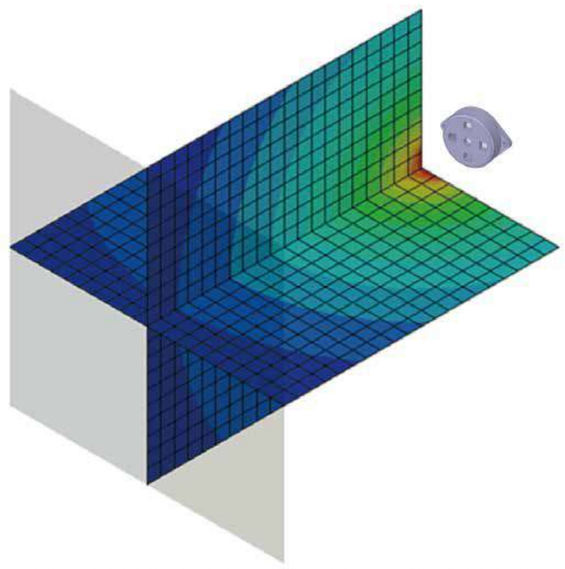
Piezoelectric Acoustic Components

独自の積層技術および電極接続技術により、高音圧を実現

Proprietary multilayering technology and electrode connecting technology make possible high sound pressure.

製品構造・量産ラインの一貫設計により、製品設計の自由度が高い

There is a high degree of freedom in product design due to the integrated design of product structure/mass production line.



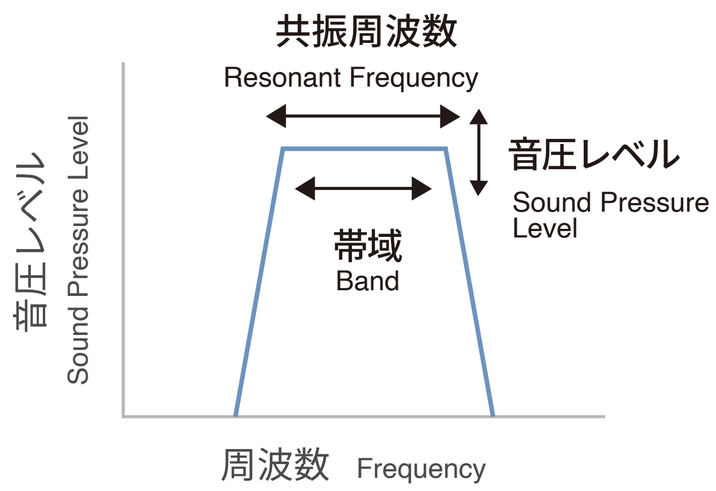
Ansys® Mechanical™ Enterprise

CAE によるシミュレーション解析設計が可能

Simulation analysis design by CAE is possible.

仕様に合わせて設計致します　We will design to your specifications.

要求事項 Requirements	HDK 保有技術 HDK owned technology
音圧レベル Sound pressure level	積層技術 Lamination technology
共振周波数 Resonant frequency	セラミック材料 Ceramic materials
	セラミック構造 Ceramic structure
帯域 Band	振動板設計 Diaphragm design
形状 Shape	ケース構造設計 Case structural design



ご要求の用途に応じ単板～積層板にて多彩な特性（音圧レベル・周波数）の各種カスタム設計および生産対応可能

Various custom designs and production with a variety of characteristics (sound pressure level, resonance frequency, band, etc.) are possible by using the plates from single to multilayer according to the required application.

SPECIFICATIONS

音圧レベル Sound Pressure Level	共振周波数 Resonant Frequency	帯域 Band	入力電圧 Input Voltage	動作温度範囲 Operating Temperature Range
60 ～ 100dB	2 ～ 4kHz	0.1 ～ 1kHz	Max.30V $_{P-P}$	-40 ～ +85°C

APPLICATION

- 車載部品　Automotive devices
- 二輪部品　Motorcycle devices
- 家電製品　Home appliances

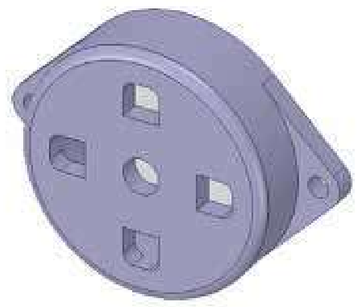
FEATURES

小型、軽量で消費電力が少ない

Small and light weight, low power consumption

寿命は半永久的で信頼性が高い

Reliable, perpetual life



HDK HOKURIKU